

NCS2535

Product Preview

Triple 1.0 GHz Current Feedback Op Amp with Enable Feature

NCS2535 is a triple 1.0 GHz current feedback monolithic operational amplifier featuring high slew rate and low differential gain and phase error. The current feedback architecture allows for a superior bandwidth and low power consumption. This device features an enable pin.

Features

- -3.0 dB Small Signal BW ($A_V = +2.0$, $V_O = 0.5 V_{p-p}$) 1.0 GHz Typ
- Slew Rate 1500 V/ μ s
- Supply Current 8.5 mA
- Input Referred Voltage Noise 6.0 nV/ $\sqrt{\text{Hz}}$
- THD -60 dBc ($f = 5.0$ MHz, $V_O = 2.0 V_{p-p}$)
- Output Current 150 mA
- Enable Pin Available
- These are Pb-Free Devices*

Applications

- High Resolution Video
- Line Driver
- High-Speed Instrumentation
- Wide Dynamic Range IF Amp

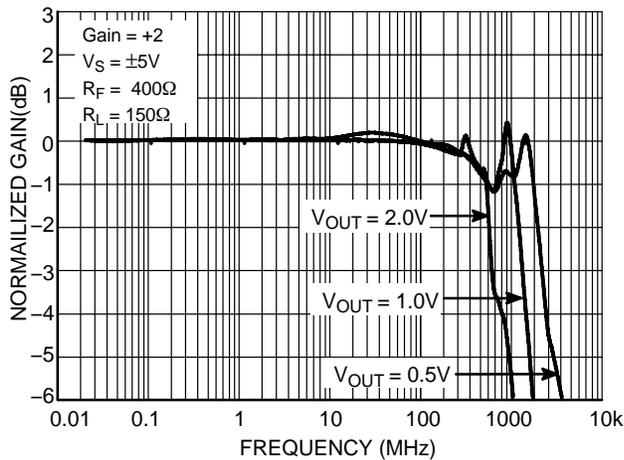


Figure 1. Frequency Response: Gain (dB) vs. Frequency, $A_V = +2.0$

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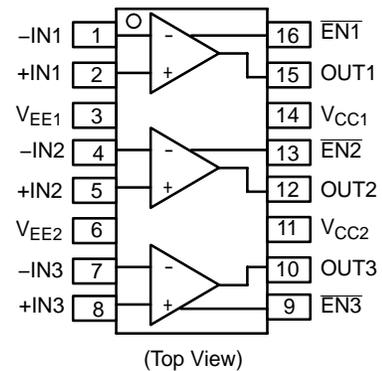
<http://onsemi.com>

MARKING DIAGRAM



2535 = NCS2535
 A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week

TSSOP-16 PINOUT



ORDERING INFORMATION

Device	Package	Shipping†
NCS2535DTBG	TSSOP-16	96 Units/Rail
NCS2535DTBR2G	TSSOP-16	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN FUNCTION DESCRIPTION

Pin	Symbol	Function	Equivalent Circuit
9, 12, 15	OUTx	Output	
3, 6	V _{EE}	Negative Power Supply	
2, 5, 8	+INx	Non-inverted Input	
1, 4, 7	-INx	Inverted Input	See Above
11, 14	V _{CC}	Positive Power Supply	
10, 13, 16	EN	Enable	

ENABLE PIN TRUTH TABLE

	High	Low*
Enable	Disabled	Enabled

*Default open state

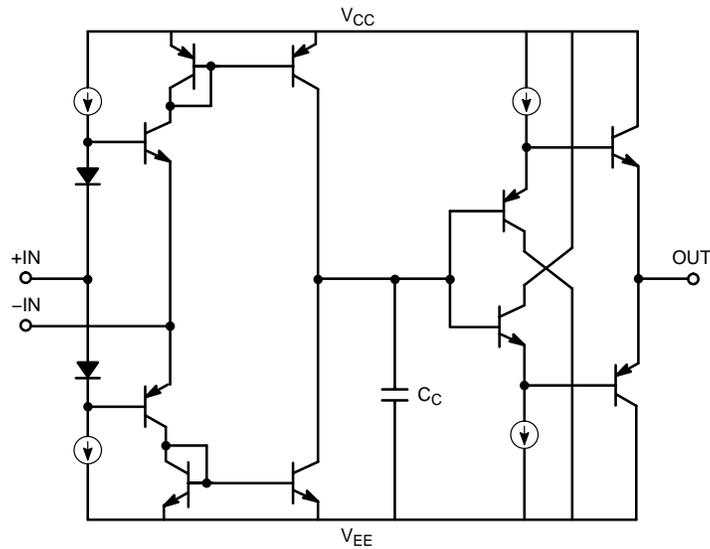


Figure 2. Simplified Device Schematic

ATTRIBUTES

Characteristics	Value
ESD	
Human Body Model	2.0 kV (Note 1)
Machine Model	200 V
Charged Device Model	1.0 kV
Moisture Sensitivity (Note 2)	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in

1. 0.8 kV between the input pairs +IN and -IN pins only. All other pins are 2.0 kV.
2. For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit
Power Supply Voltage	V_S	11	Vdc
Input Voltage Range	V_I	$\leq V_S$	Vdc
Input Differential Voltage Range	V_{ID}	$\leq V_S$	Vdc
Output Current	I_O	100	mA
Maximum Junction Temperature (Note 3)	T_J	150	°C
Operating Ambient Temperature	T_A	-40 to +85	°C
Storage Temperature Range	T_{stg}	-60 to +150	°C
Power Dissipation	P_D	(See Graph)	mW
Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	156	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

3. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded.

MAXIMUM POWER DISSIPATION

The maximum power that can be safely dissipated is limited by the associated rise in junction temperature. For the plastic packages, the maximum safe junction temperature is 150°C. If the maximum is exceeded momentarily, proper circuit operation will be restored as soon as the die temperature is reduced. Leaving the device in the “overheated” condition for an extended period can result in device damage. To ensure proper operation, it is important to observe the derating curves.

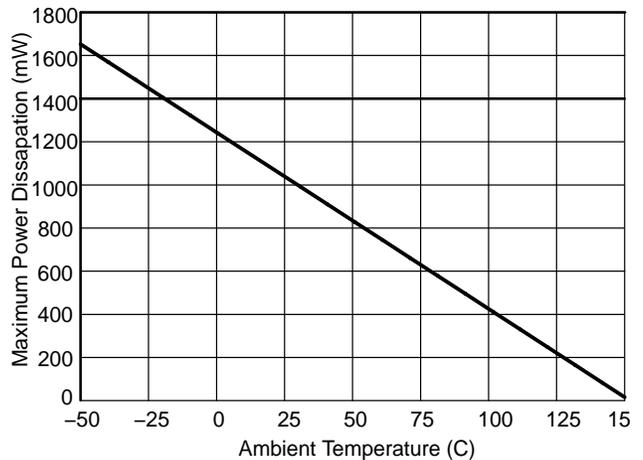


Figure 3. Power Dissipation vs. Temperature

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = +5.0\text{ V}$, $V_{EE} = -5.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $R_L = 150\ \Omega$ to GND, $R_F = 400\ \Omega$, $A_V = +2.0$, Enable is left open, unless otherwise specified).

Symbol	Characteristic	Conditions	Min	Typ	Max	Unit
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FREQUENCY DOMAIN PERFORMANCE

BW	Bandwidth 3.0 dB Small Signal 3.0 dB Large Signal	$A_V = +2.0$, $V_O = 0.5\text{ V}_{p-p}$ $A_V = +2.0$, $V_O = 2.0\text{ V}_{p-p}$		1000 450		MHz
GF _{0.1dB}	0.1 dB Gain Flatness Bandwidth	$A_V = +2.0$		120		MHz
dG	Differential Gain	$A_V = +2.0$, $R_L = 150\ \Omega$, $f = 3.58\text{ MHz}$		0.01		%
dP	Differential Phase	$A_V = +2.0$, $R_L = 150\ \Omega$, $f = 3.58\text{ MHz}$		0.01		°

TIME DOMAIN RESPONSE

SR	Slew Rate	$A_V = +2.0$, $V_{step} = 2.0\text{ V}$		1500		V/ μs
t_s	Settling Time 0.01% 0.1%	$A_V = +2.0$, $V_{step} = 2.0\text{ V}$ $A_V = +2.0$, $V_{step} = 2.0\text{ V}$		9.0 7.0		ns
t_r t_f	Rise and Fall Time	(10%–90%) $A_V = +2.0$, $V_{step} = 2.0\text{ V}$		1.5		ns
t_{ON}	Turn-on Time			55		ns
t_{OFF}	Turn-off Time			55		ns

HARMONIC/NOISE PERFORMANCE

THD	Total Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 2.0\text{ V}_{p-p}$		-60		dBc
HD2	2nd Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 2.0\text{ V}_{p-p}$		-62		dBc
HD3	3rd Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 2.0\text{ V}_{p-p}$		-66		dBc
IP3	Third-Order Intercept	$f = 10\text{ MHz}$, $V_O = 1.0\text{ V}_{p-p}$		34		dBm
SFDR	Spurious-Free Dynamic Range	$f = 5.0\text{ MHz}$, $V_O = 2.0\text{ V}_{p-p}$		55		dBc
e_N	Input Referred Voltage Noise	$f = 1.0\text{ MHz}$		6.0		nV/ $\sqrt{\text{Hz}}$
i_N	Input Referred Current Noise	$f = 1.0\text{ MHz}$, Inverting $f = 1.0\text{ MHz}$, Non-Inverting		10 3.0		pA/ $\sqrt{\text{Hz}}$

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = +5.0\text{ V}$, $V_{EE} = -5.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $R_L = 100\ \Omega$ to GND, $R_F = 1.2\text{ k}\Omega$, $A_V = +2.0$, Enable is left open, unless otherwise specified).

Symbol	Characteristic	Conditions	Min	Typ	Max	Unit
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DC PERFORMANCE

V_{IO}	Input Offset Voltage			0	± 5.0	mV
$\Delta V_{IO}/\Delta T$	Input Offset Voltage Temperature Coefficient			6.0		$\mu\text{V}/^\circ\text{C}$
I_{IB}	Input Bias Current	+Input (Non-Inverting), $V_O = 0\text{ V}$ -Input (Inverting), $V_O = 0\text{ V}$ (Note 4)		± 3.0 ± 6.0		μA
$\Delta I_{IB}/\Delta T$	Input Bias Current Temperature Coefficient	+Input (Non-Inverting), $V_O = 0\text{ V}$ -Input (Inverting), $V_O = 0\text{ V}$		+40 -10		nA/ $^\circ\text{C}$
V_{IH}	Input High Voltage (Enable) (Note 4)		2.5			V
V_{IL}	Input Low Voltage (Enable) (Note 4)				-2.5	V

INPUT CHARACTERISTICS

V_{CM}	Input Common Mode Voltage Range			± 3.0		V
CMRR	Common Mode Rejection Ratio	(See Graph)		55		dB
R_{IN}	Input Resistance	+Input (Non-Inverting) -Input (Inverting)		100 50		M Ω Ω
C_{IN}	Differential Input Capacitance			1.0		pF

OUTPUT CHARACTERISTICS

R_{OUT}	Output Resistance			0.1		Ω
V_O	Output Voltage Range			± 3.0		V
I_O	Output Current		± 90	± 120		mA

POWER SUPPLY

V_S	Operating Voltage Supply Range			10		V
$I_{S,ON}$	Power Supply Current – Enabled per amplifier	$V_O = 0\text{ V}$		8.5		mA
$I_{S,OFF}$	Power Supply Current – Disabled per amplifier	$V_O = 0\text{ V}$		0.11		mA
	Crosstalk	Channel to Channel, $f = 5.0\text{ MHz}$		60		dB
PSRR	Power Supply Rejection Ratio	(See Graph)		40		dB

4. Guaranteed by design and/or characterization.

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = +2.5\text{ V}$, $V_{EE} = -2.5\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $R_L = 150\ \Omega$ to GND, $R_F = 400\ \Omega$, $A_V = +2.0$, Enable is left open, unless otherwise specified).

Symbol	Characteristic	Conditions	Min	Typ	Max	Unit
--------	----------------	------------	-----	-----	-----	------

FREQUENCY DOMAIN PERFORMANCE

BW	Bandwidth 3.0 dB Small Signal 3.0 dB Large Signal	$A_V = +2.0$, $V_O = 0.5\text{ V}_{p-p}$ $A_V = +2.0$, $V_O = 1.0\text{ V}_{p-p}$		600 300		MHz
$GF_{0.1dB}$	0.1 dB Gain Flatness Bandwidth	$A_V = +2.0$		100		MHz
dG	Differential Gain	$A_V = +2.0$, $R_L = 150\ \Omega$, $f = 3.58\text{ MHz}$		0.01		%
dP	Differential Phase	$A_V = +2.0$, $R_L = 150\ \Omega$, $f = 3.58\text{ MHz}$		0.01		°

TIME DOMAIN RESPONSE

SR	Slew Rate	$A_V = +2.0$, $V_{step} = 1.0\text{ V}$		1000		V/ μs
t_s	Settling Time 0.01% 0.1%	$A_V = +2.0$, $V_{step} = 1.0\text{ V}$ $A_V = +2.0$, $V_{step} = 1.0\text{ V}$		12 9.0		ns
t_r t_f	Rise and Fall Time	(10%–90%) $A_V = +2.0$, $V_{step} = 1.0\text{ V}$		2.0		ns
t_{ON}	Turn-on Time			55		ns
t_{OFF}	Turn-off Time			55		ns

HARMONIC/NOISE PERFORMANCE

THD	Total Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 1.0\text{ V}_{p-p}$		-60		dBc
HD2	2nd Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 1.0\text{ V}_{p-p}$		-62		dBc
HD3	3rd Harmonic Distortion	$f = 5.0\text{ MHz}$, $V_O = 1.0\text{ V}_{p-p}$		-66		dBc
IP3	Third-Order Intercept	$f = 10\text{ MHz}$, $V_O = 0.5\text{ V}_{p-p}$		28		dBm
SFDR	Spurious-Free Dynamic Range	$f = 5.0\text{ MHz}$, $V_O = 1.0\text{ V}_{p-p}$		55		dBc
e_N	Input Referred Voltage Noise	$f = 1.0\text{ MHz}$		6.0		nV/ $\sqrt{\text{Hz}}$
i_N	Input Referred Current Noise	$f = 1.0\text{ MHz}$, Inverting $f = 1.0\text{ MHz}$, Non-Inverting		10 3.0		pA/ $\sqrt{\text{Hz}}$

DC ELECTRICAL CHARACTERISTICS ($V_{CC} = +2.5\text{ V}$, $V_{EE} = -2.5\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $R_L = 100\ \Omega$ to GND, $R_F = 1.2\text{ k}\Omega$, $A_V = +2.0$, Enable is left open, unless otherwise specified).

Symbol	Characteristic	Conditions	Min	Typ	Max	Unit
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DC PERFORMANCE

V_{IO}	Input Offset Voltage			0	± 5.0	mV
$\Delta V_{IO}/\Delta T$	Input Offset Voltage Temperature Coefficient			6.0		$\mu\text{V}/^\circ\text{C}$
I_{IB}	Input Bias Current	+Input (Non-Inverting), $V_O = 0\text{ V}$ -Input (Inverting), $V_O = 0\text{ V}$ (Note 5)		± 3.0 ± 6.0		μA
$\Delta I_{IB}/\Delta T$	Input Bias Current Temperature Coefficient	+Input (Non-Inverting), $V_O = 0\text{ V}$ -Input (Inverting), $V_O = 0\text{ V}$		+40 -10		nA/ $^\circ\text{C}$
V_{IH}	Input High Voltage (Enable) (Note 5)		1.875			V
V_{IL}	Input Low Voltage (Enable) (Note 5)				-1.875	V

INPUT CHARACTERISTICS

V_{CM}	Input Common Mode Voltage Range			± 1.0		V
CMRR	Common Mode Rejection Ratio	(See Graph)		55		dB
R_{IN}	Input Resistance	+Input (Non-Inverting) -Input (Inverting)		100 50		M Ω Ω
C_{IN}	Differential Input Capacitance			1.0		pF

OUTPUT CHARACTERISTICS

R_{OUT}	Output Resistance			0.1		Ω
V_O	Output Voltage Range			± 1.2		V
I_O	Output Current		± 90	± 120		mA

POWER SUPPLY

V_S	Operating Voltage Supply Range			5.0		V
$I_{S,ON}$	Power Supply Current – Enabled per amplifier	$V_O = 0\text{ V}$		8.0		mA
$I_{S,OFF}$	Power Supply Current – Disabled per amplifier	$V_O = 0\text{ V}$		0.09		mA
	Crosstalk	Channel to Channel, $f = 5.0\text{ MHz}$		60		dB
PSRR	Power Supply Rejection Ratio	(See Graph)		40		dB

5. Guaranteed by design and/or characterization.

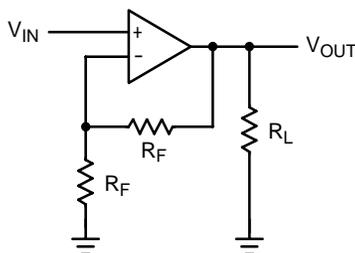


Figure 4. Typical Test Setup
($A_V = +2.0$, $R_F = 400\ \Omega$, $R_L = 150\ \Omega$)

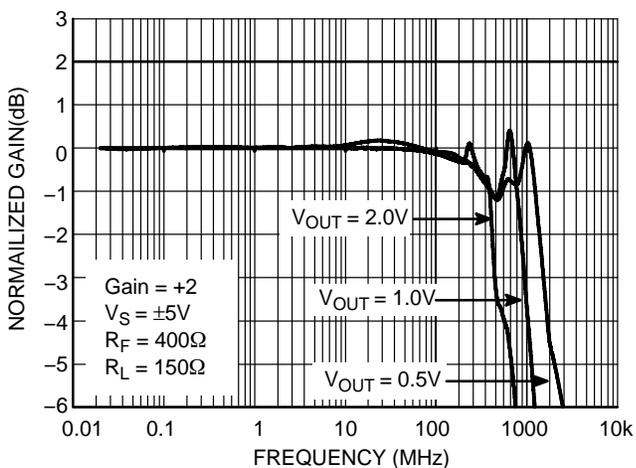


Figure 5. Frequency Response:
Gain (dB) vs. Frequency
Av = +2.0

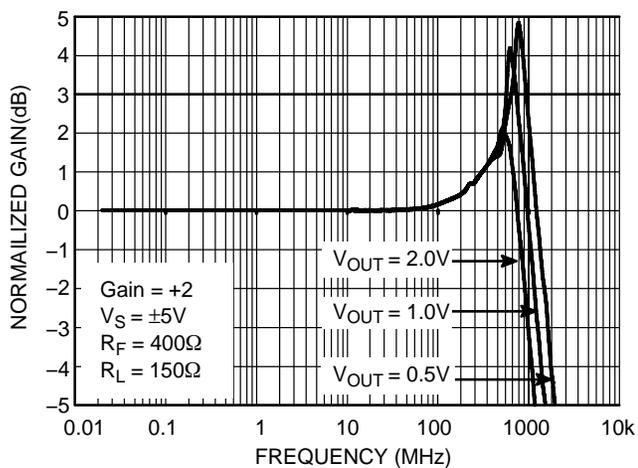


Figure 6. Frequency Response:
Gain (dB) vs. Frequency
Av = +1.0

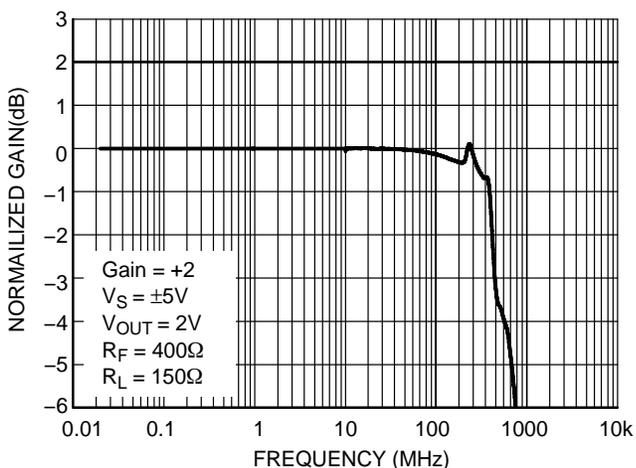


Figure 7. Large Signal Frequency Response
Gain (dB) vs. Frequency

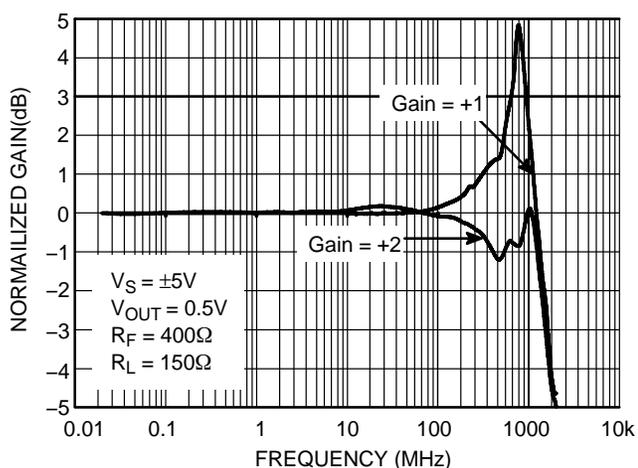


Figure 8. Small Signal Frequency Response
Gain (dB) vs. Frequency

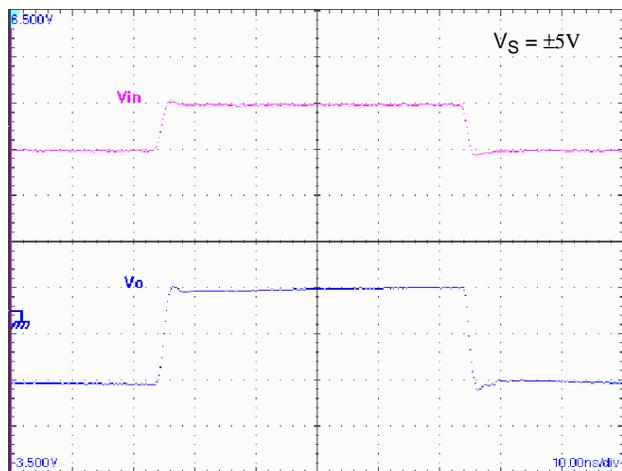


Figure 9. Small Signal Step Response
Vertical: 1V/div
Horizontal: 10ns/div

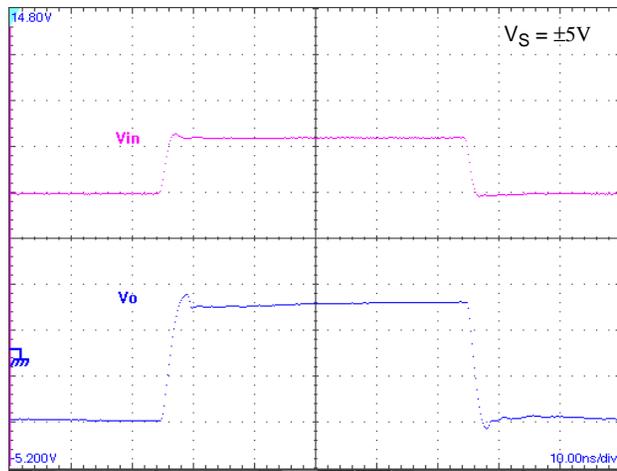


Figure 10. Large Signal Step Response
Vertical: 2V/div
Horizontal: 10ns/div

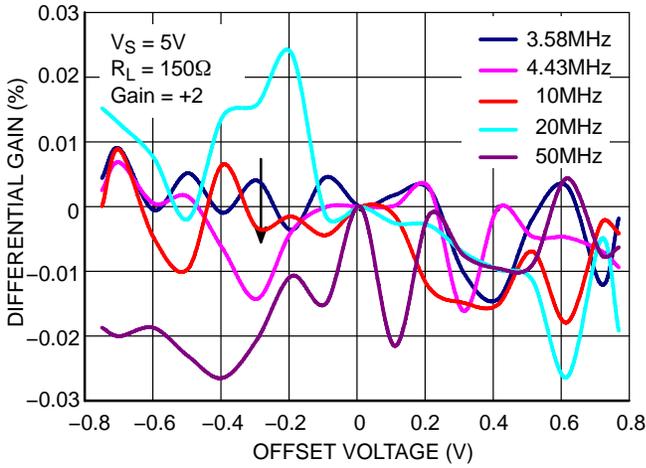


Figure 11. Differential Gain

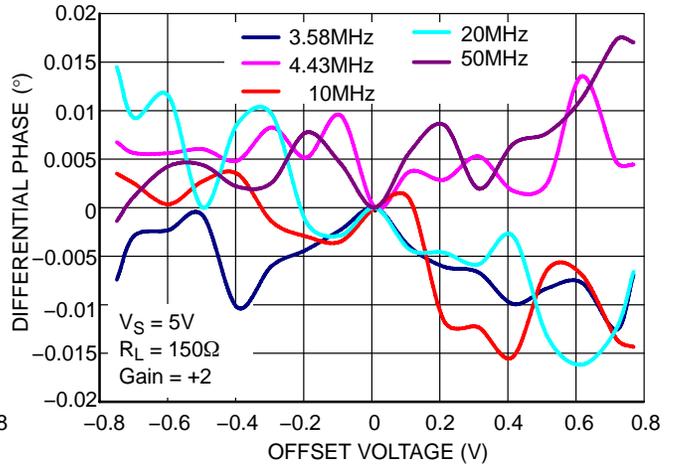


Figure 12. Differential Phase

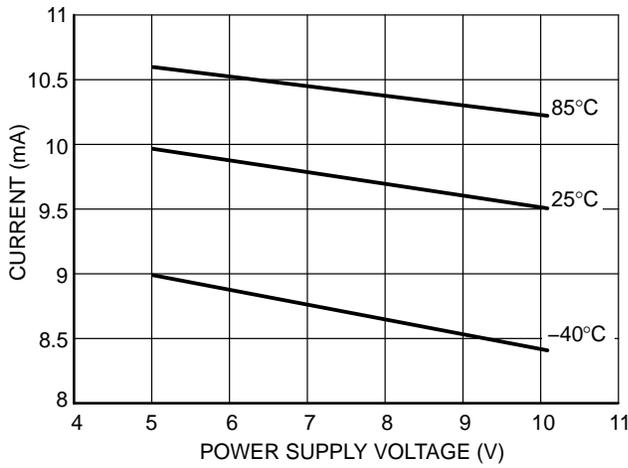


Figure 13. Supply Current vs. Power Supply (Enabled)

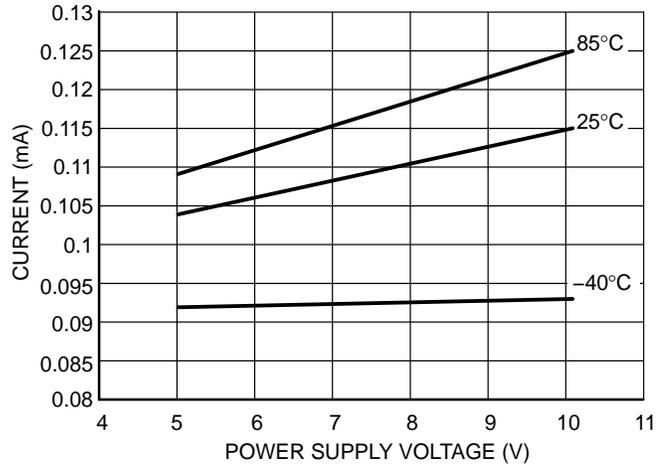


Figure 14. Supply Current vs. Power Supply (Disabled)

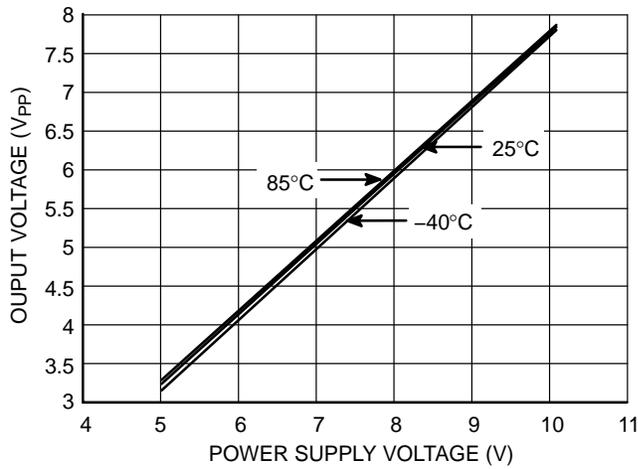


Figure 15. Output Voltage Swing vs. Supply Voltage

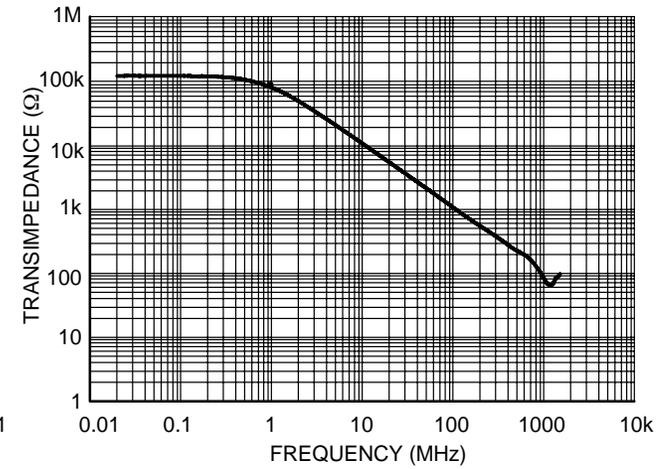


Figure 16. Transimpedance (ROL) vs. Frequency

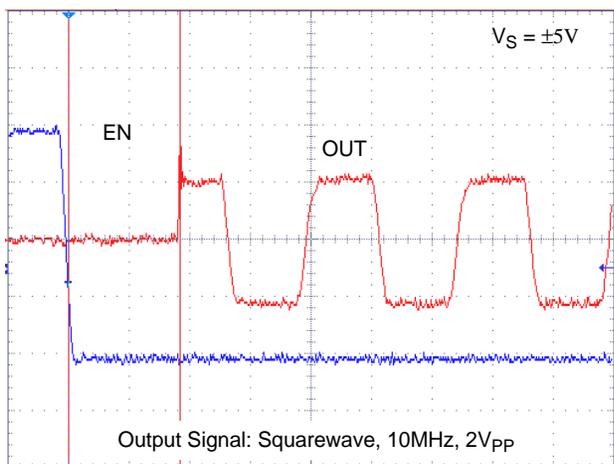


Figure 17. Turn ON Time Delay
Vertical: (EN) 500mV/div (OUT) 1V/div
Horizontal: 40ns/div

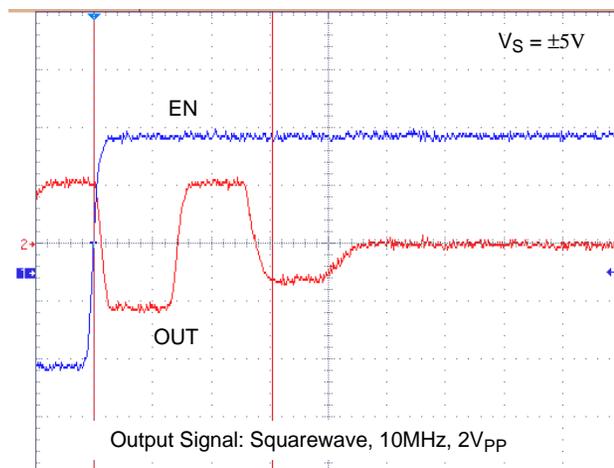


Figure 18. Turn OFF Time Delay
Vertical: (EN) 500mV/div (OUT) 1V/div
Horizontal: 40ns/div

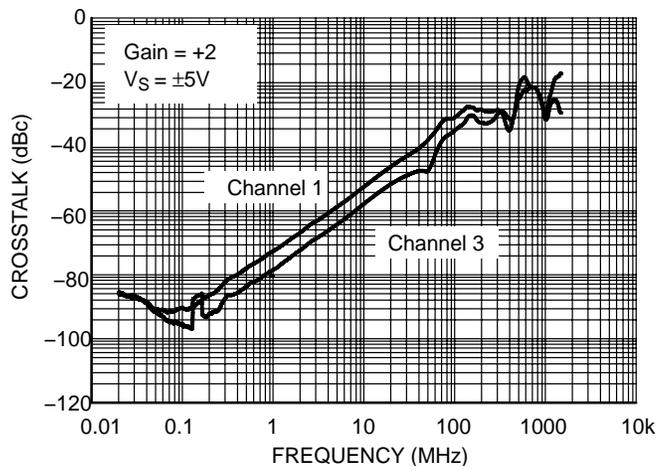


Figure 19. Crosstalk (dBc) vs. Frequency

General Design Considerations

The current feedback amplifier is optimized for use in high performance video and data acquisition systems. For current feedback architecture, its closed-loop bandwidth depends on the value of the feedback resistor. The closed-loop bandwidth is not a strong function of gain, as is for a voltage feedback amplifier, as shown in Figure 20.

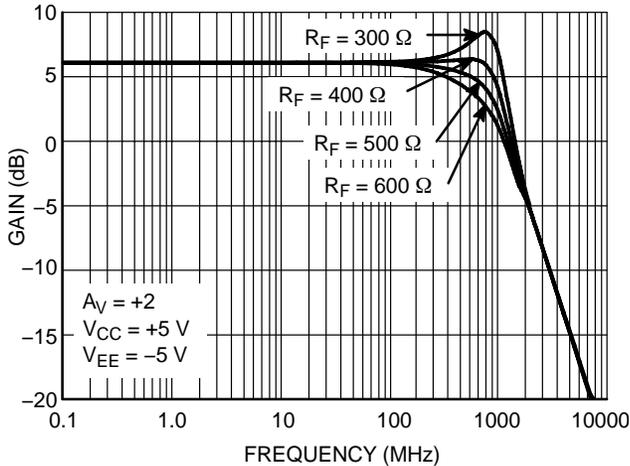


Figure 20. Frequency Response vs. R_F

The -3.0 dB bandwidth is, to some extent, dependent on the power supply voltages. By using lower power supplies, the bandwidth is reduced, because the internal capacitance increases. Smaller values of feedback resistor can be used at lower supply voltages, to compensate for this affect.

Feedback and Gain Resistor Selection for Optimum Frequency Response

A current feedback operational amplifier’s key advantage is the ability to maintain optimum frequency response independent of gain by using appropriate values for the feedback resistor. To obtain a very flat gain response, the feedback resistor tolerance should be considered as well. Resistor tolerance of 1% should be used for optimum flatness. Normally, lowering R_F resistor from its recommended value will peak the frequency response and extend the bandwidth while increasing the value of R_F resistor will cause the frequency response to roll off faster. Reducing the value of R_F resistor too far below its recommended value will cause overshoot, ringing, and eventually oscillation.

Since each application is slightly different, it is worth some experimentation to find the optimal R_F for a given circuit. A value of the feedback resistor that produces ~ 0.1 dB of peaking is the best compromise between stability and maximal bandwidth. It is not recommended to

use a current feedback amplifier with the output shorted directly to the inverting input.

Printed Circuit Board Layout Techniques

Proper high speed PCB design rules should be used for all wideband amplifiers as the PCB parasitics can affect the overall performance. Most important are stray capacitances at the output and inverting input nodes as it can effect peaking and bandwidth. A space ($3/16''$ is plenty) should be left around the signal lines to minimize coupling. Also, signal lines connecting the feedback and gain resistors should be short enough so that their associated inductance does not cause high frequency gain errors. Line lengths less than $1/4''$ are recommended.

Video Performance

This device designed to provide good performance with NTSC, PAL, and HDTV video signals. Best performance is obtained with back terminated loads as performance is degraded as the load is increased. The back termination reduces reflections from the transmission line and effectively masks transmission line and other parasitic capacitances from the amplifier output stage.

ESD Protection

All device pins have limited ESD protection using internal diodes to power supplies as specified in the attributes table (see Figure 21). These diodes provide moderate protection to input overdrive voltages above the supplies. The ESD diodes can support high input currents with current limiting series resistors. Keep these resistor values as low as possible since high values degrade both noise performance and frequency response. Under closed-loop operation, the ESD diodes have no effect on circuit performance. However, under certain conditions the ESD diodes will be evident. If the device is driven into a slewing condition, the ESD diodes will clamp large differential voltages until the feedback loop restores closed-loop operation. Also, if the device is powered down and a large input signal is applied, the ESD diodes will conduct.

NOTE: Human Body Model for +IN and -IN pins are rated at 0.8kV while all other pins are rated at 2.0kV.

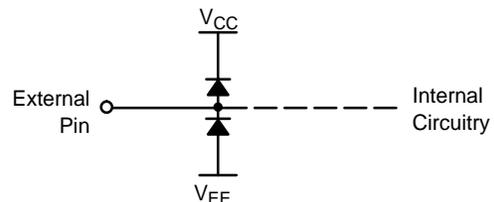
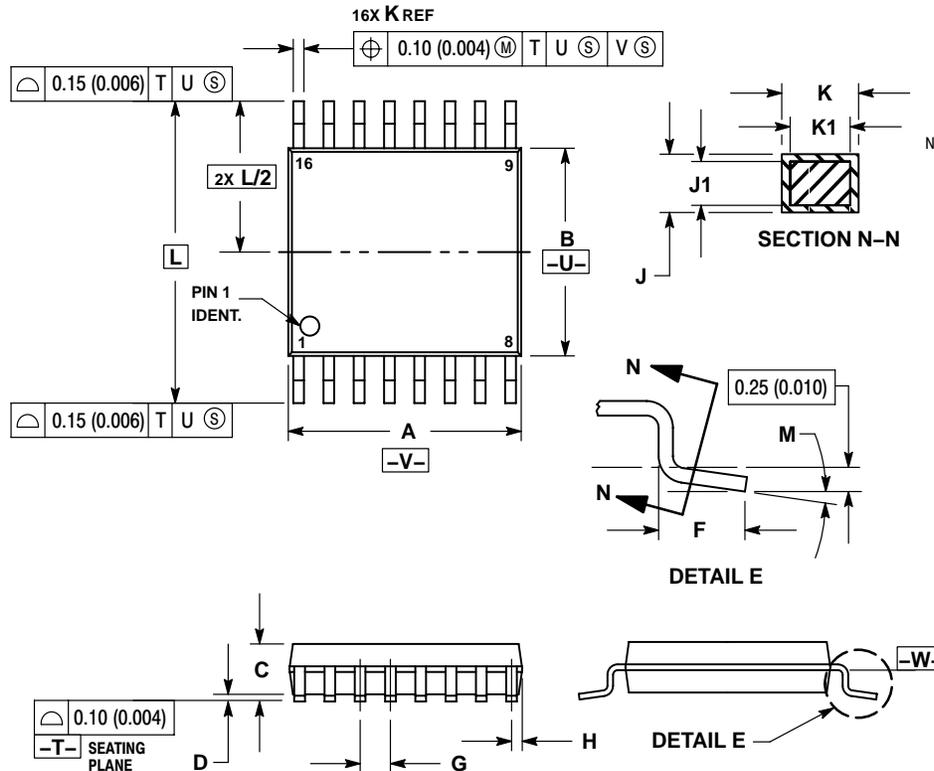


Figure 21. Internal ESD Protection

PACKAGE DIMENSIONS

TSSOP-16
DT SUFFIX
CASE 948F-01
ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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